

# **3D-System-in-Package Distributed Rover Control Module featuring SpaceWire and CAN**

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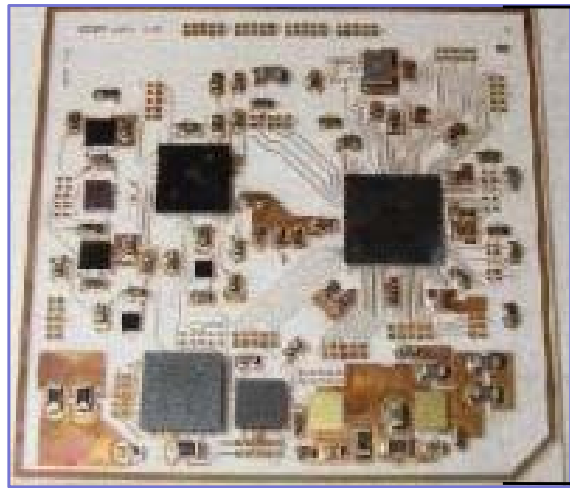
**\*\* ESA/ESTEC**



# Recap from Previous Presentation on ÅAC 3D-SiP Subsystems

- ✓ 3D-SiP Remote Terminal Unit (RTU) together with Swedish Institute of Space Physics (IRFU)
- ✓ 3D-SiP Magnetic Attitude Control System (MACS) together with ZARM Technik

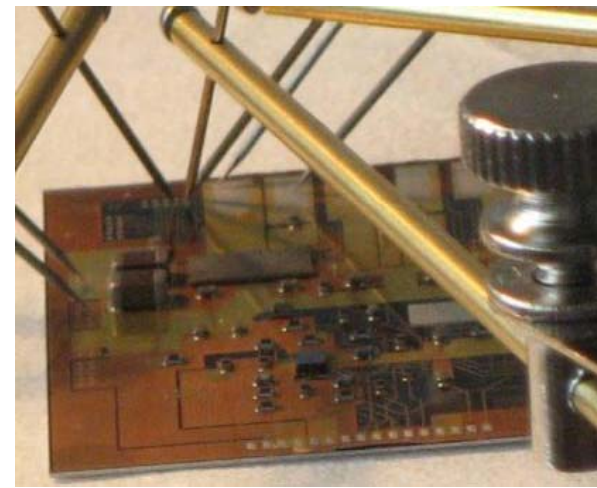
Mass: 3-4 gram  
dep. on package



RTU

33 x 33 x 1

Mass: 3-4 gram  
dep. on package



MACS

# Short Background

- ✓ Rover complexity is increasing
  - More moving/rotating nodes
  - Higher feed-back in control loops
  - Massive increase in harness and wiring

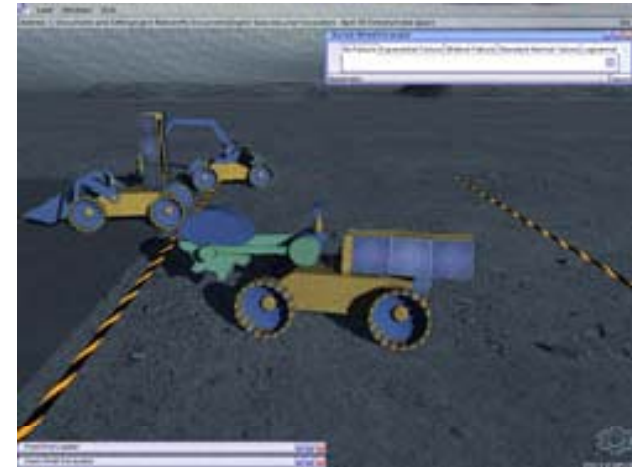


Image courtesy of NASA

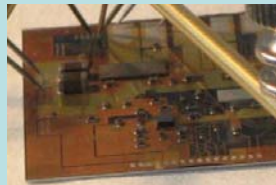
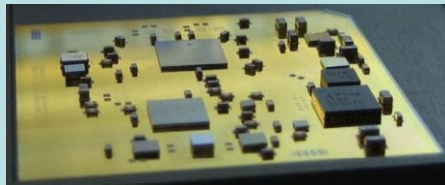
- ✓ Large increase expected in future robotic/rover missions
  - Reliable standard components necessary
  - Good opportunity to leverage development costs of 3D-SiP
  - Introduction of system-level redundancy
  - The radiation environment on Mars is relatively low. I.e. mil-spec. devices/chips can be used
- ✓ Interplanetary robotics is an area of interest for both government agencies and private companies



# μRTSD - Development Definition and Roadmap

- Develop and qualify a standardized component for motor control
- Micro **R**emote **T**erminal **S**ervo **D**river (μRTSD)

## μRTSD Flight Hardware Roadmap



RTU/MACS adaptation and manufacturing of 10 units for Technology validation and testing. TRL 6

Phase 1 – (1.5 year)

Phase 2 – Test and validation (months)

Phase 3 – QM (1 year)

μRTSD QM  
TRL 7

Phase 4 – Test and validation (months)

Phase 5 – FM (1 year)

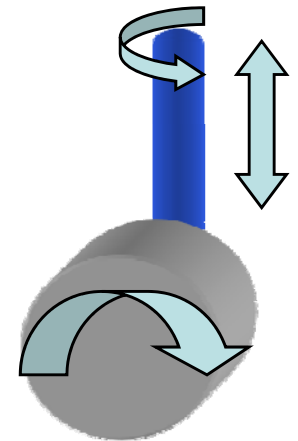
μRTSD FM  
TRL 8

FM in ~ 4 years including QA of new 3D-SiP technology. Ready for 2012



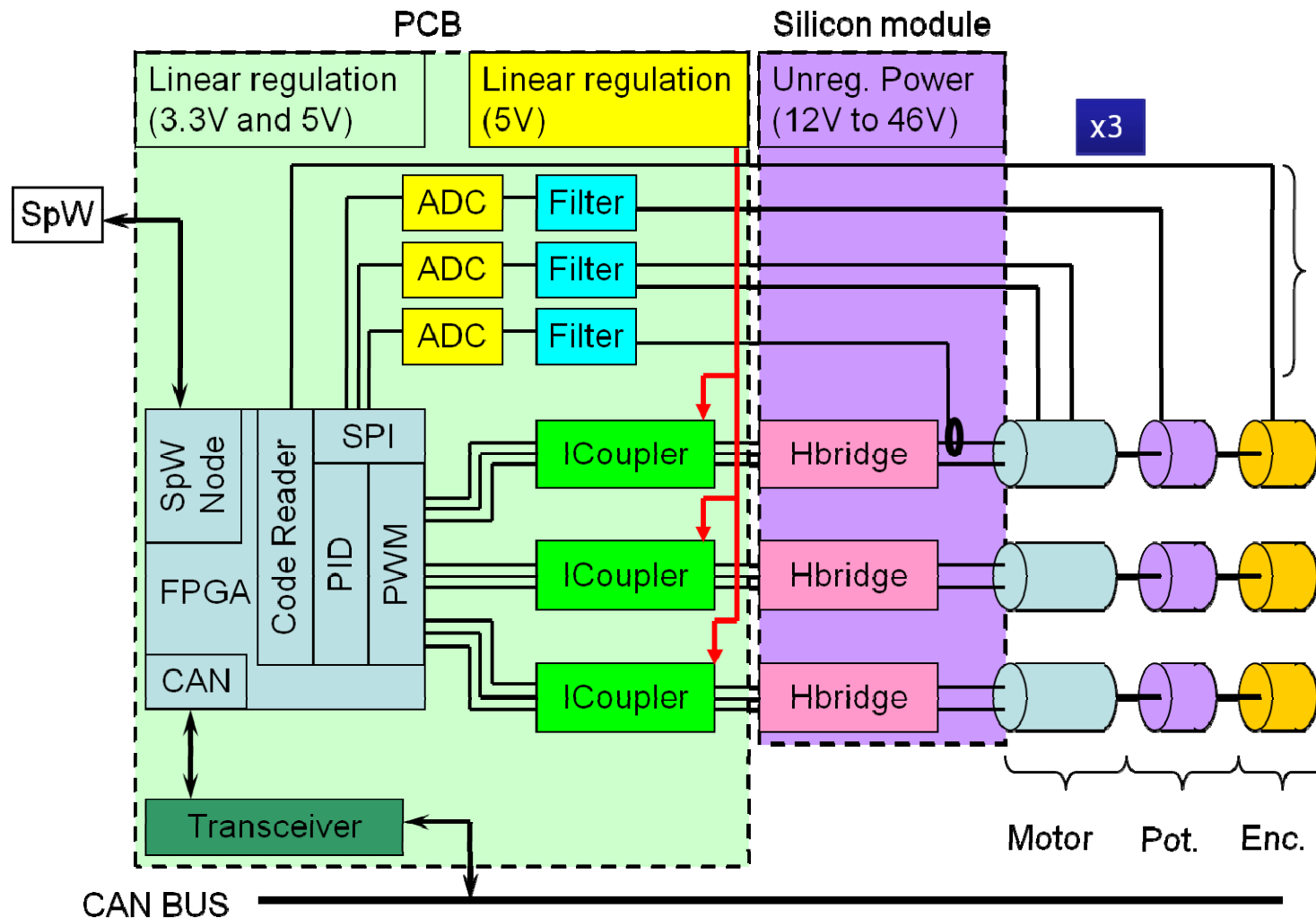
# μRTSD – First Requirements

- Distributed design
- SpaceWire (Link/Router) connection
- Controller Area Network (CAN) connection
- Optional SpaceFiber for Gbit/s transfers
- Plug 'n play
- Up to 3 motors per μRTSD
- Up to 40 V motor voltage
- Up to 3 A motor current (120 W per motor, 360 W per μRTSD)
- Up to 200 kHz pulse-width-modulation (PWM) per motor
- Up to 14 bit x 1 Msample/s in feed-back from sensors
- Localized Kalman filtering
- Built in heater
- 160 to 150 degrees C in storage temperature
- 40 to 80 degrees C in operational temperature
- Maximum 50 x 50 x 3 mm<sup>3</sup> in volume



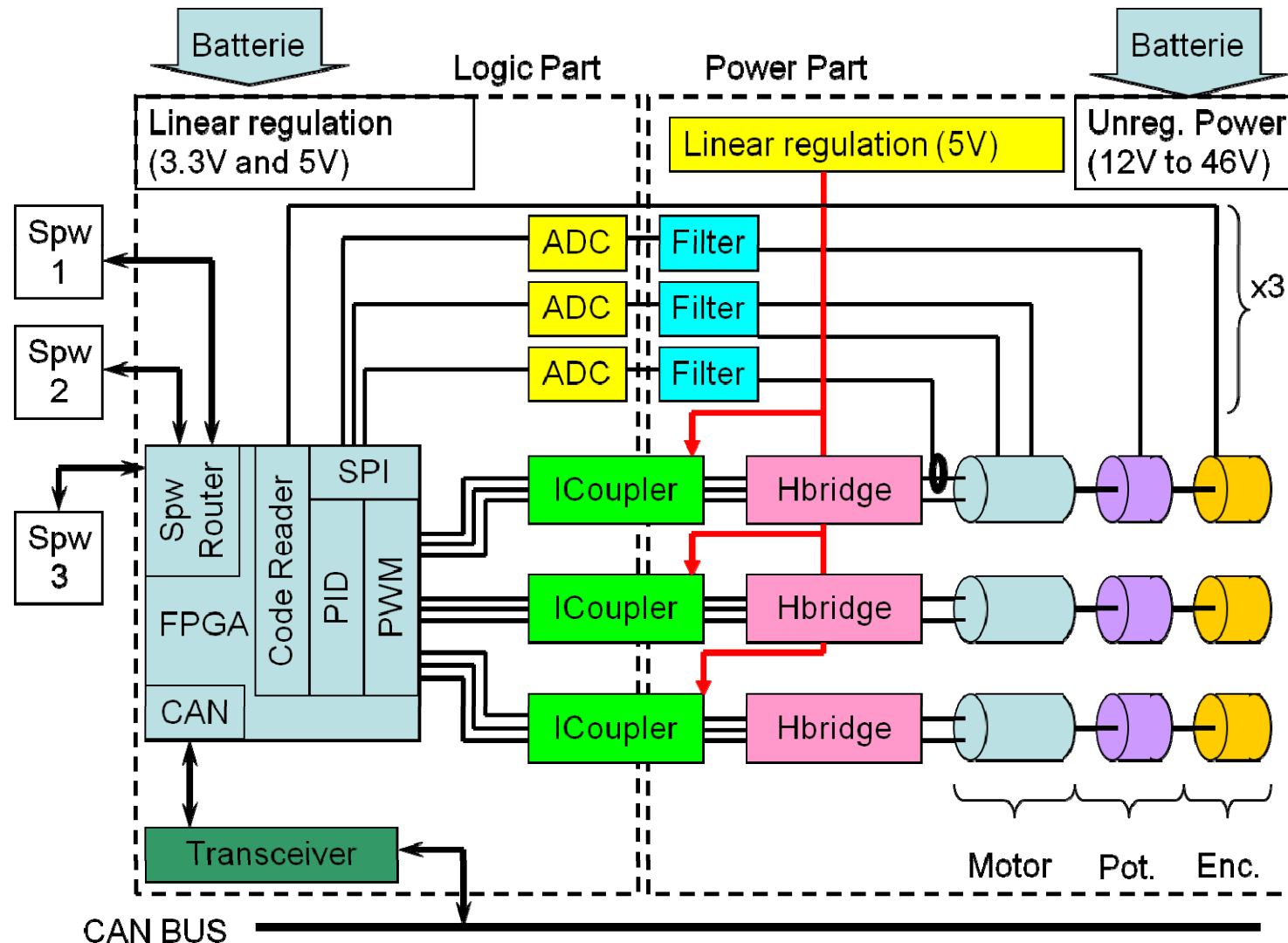
# Phase 1 – Block Diagram

- Verification of critical parts (motor drivers). Heritage claimed from RTU for the digital parts. Important to find out if galvanic isolation is needed. Phase 1 includes option to bypass ICoupler.



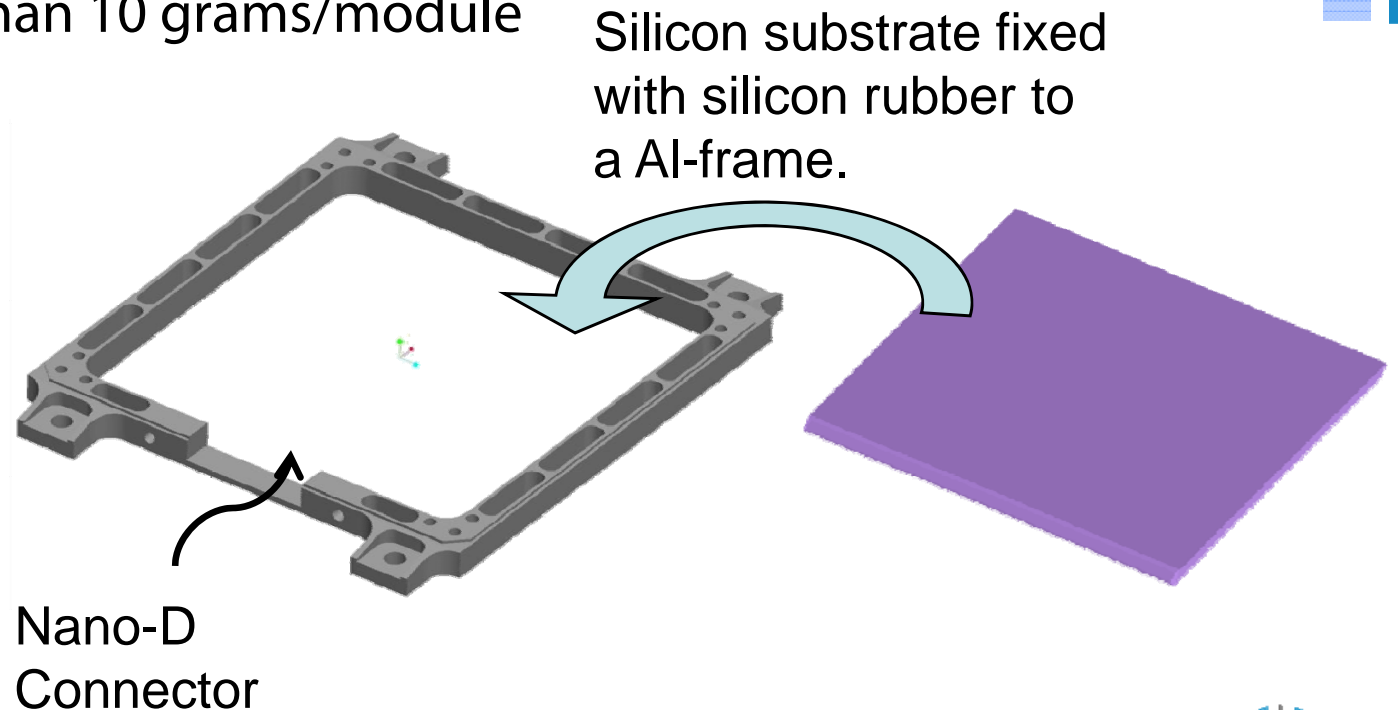
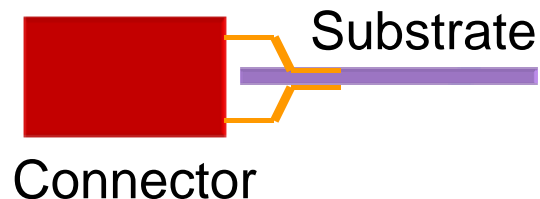
# Phase 3 – Block Diagram

- QM includes everything in 3D-SiP.
- ICoupler is still TBD from Phase 1.



## Phase 3 – QM preliminary concept design

- ✓ QM is expected to work to -160 to 150 degrees C
- ✓ The silicon rubber interface between the substrate and the protective box need further investigation
- ✓ The box protects the 3D-SiP technology from dust and provides radiation protection
- ✓ 50 x 50 x 3 mm<sup>3</sup>
- ✓ Weight: less than 10 grams/module





# Potential Implementation Examples



Image: ESA

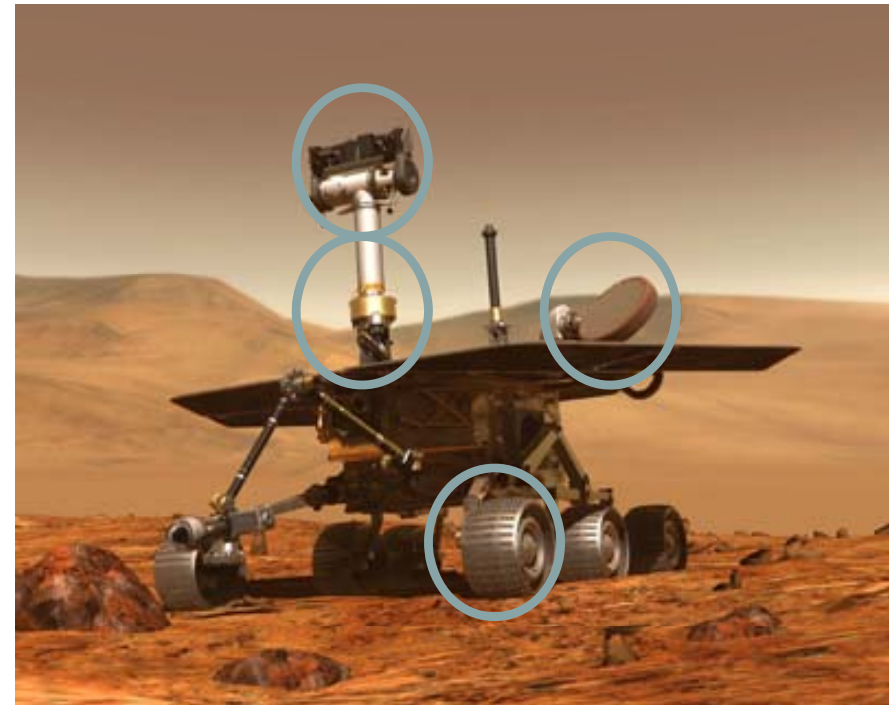


Image: NASA

# Conslusions

- Heritage from ÅAC 3D-SiP technology show that the development is feasible
- Qualification issues are to be discussed with ESA
- Enables a massive increase of payload on large complex robots and rovers
- Enables a much easier system integration as a multifunctional element (thermal properties, structural element, electrical function, and possible electromechanical function)



THANK YOU FOR YOUR ATTENTION

